

AMENDMENTS TO THE SPECIFICATION

In the Specification

Please insert the following new paragraph at line 13 on page 5:

FIGURE 7 shows wafers having metal layers deposited thereon.

Please insert the following new paragraph at line 15 on page 5:

FIGURE 8 shows wafers having metal layers thereon that have been polished.

Please replace the paragraph beginning at line 21 on page 8 with the following amended paragraph:

FIGURE 2 shows one embodiment in which a wafer processing apparatus 200 includes a metal deposition tool and a CMP tool. The metal deposition tool shown in FIGURE 2 is an electroplating tool 210 that has multiple electroplating chambers 212. FIGURE 7 shows wafers having metal layers deposited thereon. FIGURE 2 shows a schematic representation of an annealing chamber 232 on the electroplating tool 210.

Please replace the paragraph beginning at line 8 on page 9 with the following amended paragraph:

CMP tool 220 is shown in FIGURE 2 as having multiple CMP platforms 222. Alternatively, multiple CMP tools 220 can be provided for apparatus 200 or a single CMP tool 220 can provide a single CMP platform 222. FIGURE 8 shows wafers having metal layers thereon that have been polished.